

(19) World Intellectual Property Organization International Bureau





(43) International Publication Date 24 February 2005 (24.02.2005)

PCT

(10) International Publication Number WO 2005/017978 A3

(51) International Patent Classification⁷: H01L 31/032, 31/18

(21) International Application Number:

PCT/IB2004/051458

(22) International Filing Date: 13 August 2004 (13.08.2004)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

2003/6316 2004/2497 14 August 2003 (14.08.2003) ZA 30 March 2004 (30.03.2004) ZA

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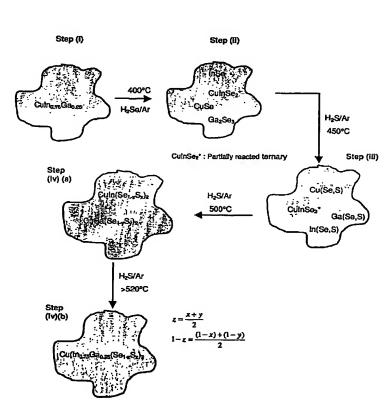
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- (81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.
- (84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM,

[Continued on next page]

(54) Title: METHOD FOR THE PREPARATION OF GROUP IB-IIIA-VIA QUATERNARY OR HIGHER ALLOY SEMICONDUCTOR FILMS



(57) Abstract: This invention relates to a method for producing group IB-IIIA-VIA quaternary or higher alloy semiconductor films wherein the method comprises the steps of (i) providing a metal film comprising a mixture of group IB and group IIIA metals; (ii) heat treating the metal film in the presence of a source of a first group VIA element (said first group VIA element hereinafter being referred to as VIA₁) under conditions to form a first film comprising a mixture of at least one binary alloy selected from the group consisting of a group IB -VIA1 alloy and a group IIIA-VIA1 alloy and at least one group IB-IIIA-VIA₁ ternary alloy (iii) optionally heat treating the first film in the presence of a source of a second group VIA element (said second group VI element hereinafter being referred to as VIA2) under conditions to convert the first film into a second film comprising at least one alloy selected from the group consisting of a group IB-VIA1-VIA2 alloy and a group IIIA-VIA1-VIA2 alloy; and the at least one group IB-III-VIA1 ternary alloy of step (ii); (iv) heat treating either the first film or second film to form a group IB-IIIA-VIA quaternary or higher alloy semiconductor film.

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ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

Published:

- with international search report
- (88) Date of publication of the international search report:
 13 October 2005